

<b>Theme: Label/Label Location</b>					
Name Schreiber Simon	Dept. R&D/HWR-MUL	path, file name L:\Projekte\IP00178 BASE Antrieb\03 Entwicklung\02 Elektronik\01 Hardware\01_AllgemeineDokumentation\BT- Zertifizierung\BGM210P Modul\03 Unterlagen für USA_Kanada Zulassung\08_Label Location.docx	date 18.12.2023	sheet 1	of 2

## 1 Labeling of the Module Z139.910

The Label on the Module will be placed at the indicated Position.

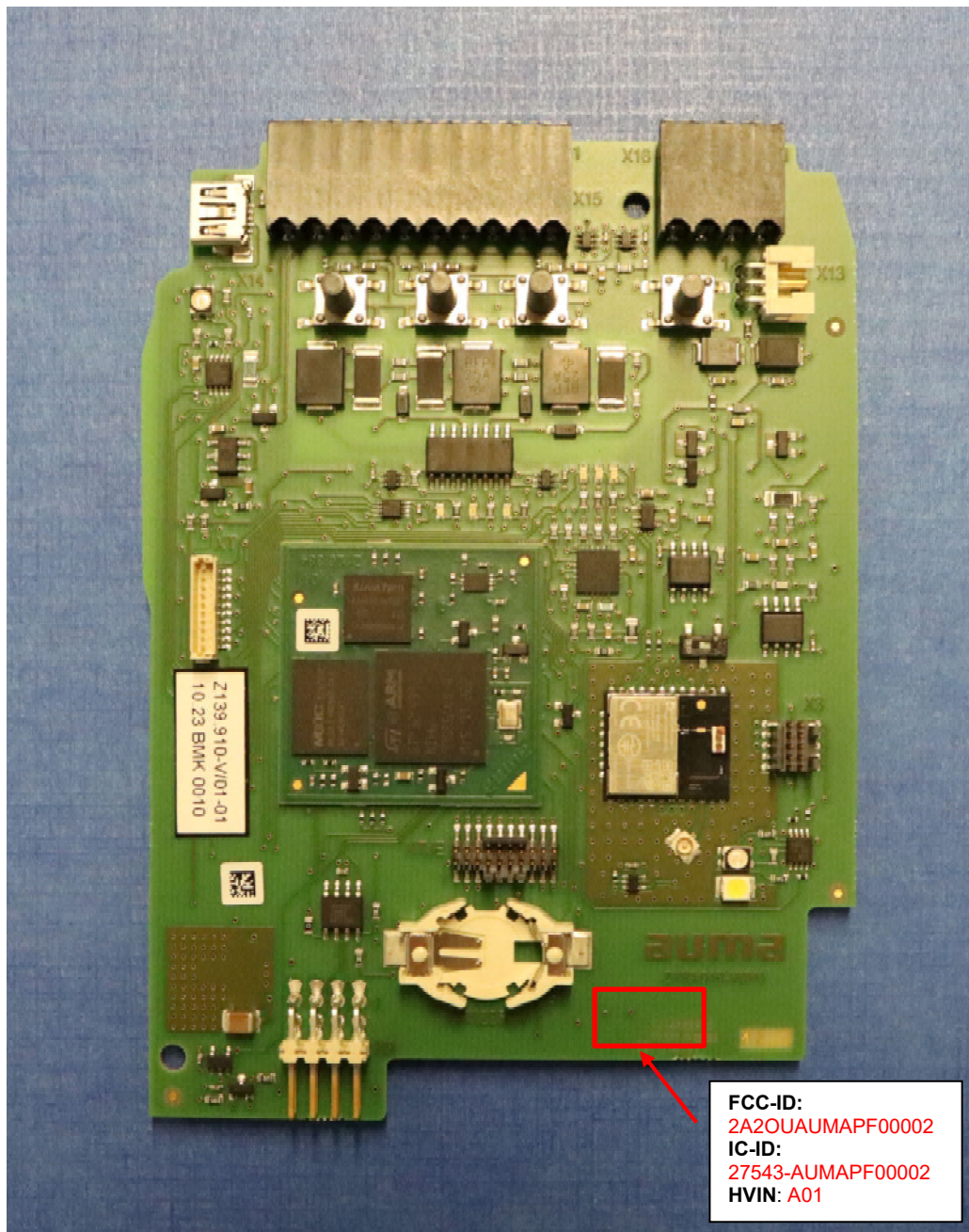


Figure 1: Label Location on Module Z139.910

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Schreiber Simon	R&D/HWR-MUL	L:\Projekte\IP00178 BASE Antrieb\03 Entwicklung\02 Elektronik\01 Hardware\01_AllgemeineDokumentation\BT- Zertifizierung\BGM210P Modul\03 Unterlagen für USA_Kanada Zulassung\08_Label Location.docx	18.12.2023	2	2

## 2 Labelling of Endproduct

The end products must be marked legibly from the outside with the following label:

Contains FCC ID: **2A2OUAUMAPF00002**

Cointains IC ID: **27543-AUMAPF00002**